

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Wen-Chih YANG	08/07/2009
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDCUTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12433356
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	24061.1186
NAME OF SUBMITTER:	David M. O'Dell
<p>Total Attachments: 3</p> <p>source=1186_assignment#page1.tif</p> <p>source=1186_assignment#page2.tif</p>	

CH \$40.00 12433356

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PATENT
REEL: 023204 FRAME: 0634

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|---|
| (1) | Jin-Aun Ng | of | 6F, No. 7, Jinshan N. 1st Road, East District
Hsinchu City 300, Taiwan, R.O.C. |
| (2) | Wen-Chih Yang | of | No.12, Lane 416, Sec. 1, Zhongshan Rd.,
Changhua City, Changhua County 500, Taiwan (R.O.C.). |
| (3) | Chien-Liang Chen | of | 4F, No. 176, Guandong Rd., East District
Hsinchu City 300, Taiwan, R.O.C. |
| (4) | Chung-Hau Fei | of | 3F, No. 10, Lane 178, Guandong Rd., East District
Hsinchu City 300, Taiwan, R.O.C. |
| (5) | Maxi Chang | of | 8F-13, No. 8, Nanya E. Road
Banciao City, Taipei County 220, Taiwan, R.O.C. |
| (6) | Bao-Ru Young | of | No. 7, Lane 1, Liujia 2nd Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C. |
| (7) | Harry Chuang | of | 18-59 Lane 85, Fu-Chuan Street
Hsin-Chu City, Taiwan, R.O.C. |

have invented certain improvements in

**A BALANCE STEP-HEIGHT SELECTIVE BI-CHANNEL
STRUCTURE ON HKMG DEVICES**

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on and assigned application no. and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications

for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jin-Aun Ng

Residence Address: 6F, No. 7, Jinshan N. 1st Road, East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Wen-Chih Yang

Residence Address: No.12, Lane 416, Sec. 1, Zhongshan Rd.,
Changhua City, Changhua County 500, Taiwan (R.O.C.).

Dated: 2008/8/7

Wen Chih Yang
Inventor Signature

Inventor Name: Chien-Liang Chen

Residence Address: 4F, No. 176, Guandong Rd., East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Chung-Hau Fei

Residence Address: 3F, No. 10, Lane 178, Guandong Rd., East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Maxi Chang

Residence Address: 8F-13, No. 8, Nanya E. Road
Banciao City, Taipei County 220, Taiwan, R.O.C.

Dated: _____

Inventor Signature

Inventor Name: Bao-Ru Young

Residence Address: No. 7, Lane 1, Liujia 2nd Street
Zhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: _____

Inventor Signature
